1. Disassembly Procedures

S1 Turn off power

S2 Place the monitor on a soft cloth or cushion

Carefully slide and remove the I/O cover from the monitor.



Disconnect the cables from the monitor and slide them out through the cablemanagement slot on the stand riser



S4 Press and hold the stand release button



S5 Lift the stand up and away from the monitor.



S6 Unlock 4 screws on rear cover

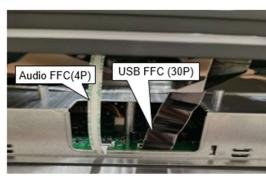
Use hands or scraper bar to disassemble Rear Cover from the monitor.

Notice the disassembly order: Left Side=> Top Side=> Right Side=> Bottom Side



(Screw Torque: 8-10 kgf)

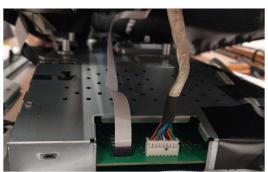
Remove USB FFC and Audio FFC from I/F BD



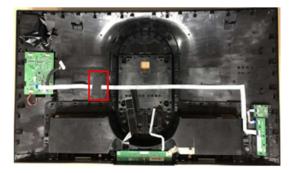
Disconnect LED Driver BD wire and CTRL FFC cable from I/F BD

Take off Rear Cover

S8

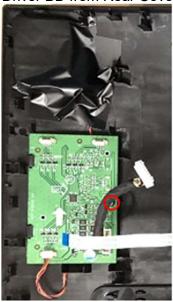


Tear off a tape from CTRL FFC cable on Rear Cover



S10 Remove all cables from LED Driver BD

Unlock 1 screw and disassemble LED Driver BD from Rear Cover



(Screw Torque: 4.5±0.5 kgf)

S11 Tear off an adhesive tape from LED BD wire on Rear Cover



S12 Tear off "MYLAR HEAD LOGO" from cover LOGO LENS



S13 Disconnect LED BD wire from LED BD

Disassemble LED BD from Rear Cover



S14 Remove a conductive foam from conductive cloth



Remove a conductive cloth from the right USB screw and Rear Cover



S16 Unlock 2 screws to disassemble USB BD from Rear Cover



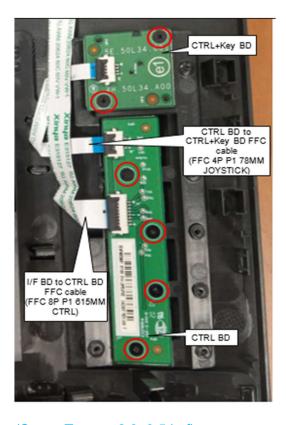
(Screw Torque: 4.5±0.5 kgf)

S17 Disconnect USB FFC and Audio FFC from USB BD



Remove FFC cable from Rear Cover, CTRL BD and CTRL+KEY BD

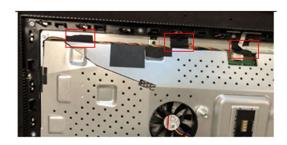
Unlock 6 screws to disassemble CTRL BD and CTRL+KEY BD from Rear Cover

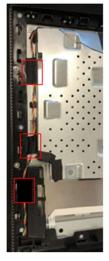


(Screw Torque: 2.0±0.5 kgf)

S19 Tear off 6 tapes on Backlight Wire

Disconnect Backlight Wire from I/F BD

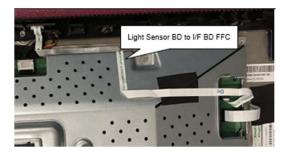




S20 Disconnect "CTRL+LENS BD FFC" from I/F BD and remove it from Panel and Main SHD

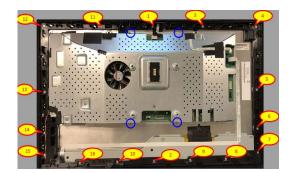


S21 Disconnect Light Sensor BD FFC from I/F BD and remove it from Panel and Main SHD



S22 Unlock MF screw*16 to disassemble the Middle Frame from Panel (Yellow Mark)

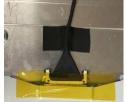
Unlock 4 screws to disassemble Main SHD from Panel (Blue Mark)



(Screw Torque-MF: 4.5±0.5 kgf) (Screw Torque-Main SHD: 4.0±0.5 kgf)

S23 Tear off an acetate tape and a tensile tape from EDP cable





S24 Disconnect EDP cable from Panel

Take off Main SHD from Panel



S25 Tear off the adhesive tape from the connector of Backlight wire

Disconnect Backlight Wire from Panel

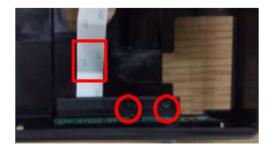




S26 Disassemble Light Sensor BD from Middle Frame



S27 Unlock 2 screws to disassemble Power Button module from Middle Frame



(Screw Torque:1.1±0.1kgf)

S28 Disconnect FFC cable from "CTRL+LENS BD" (Power CTRL BD)



Tear off "MYLAR PWR-LENS" from "CTRL+LENS BD" (Power CTRL BD)



Unlock 2 screws to disassemble "CTRL+LENS BD" (Power CTRL BD) from Power Button



(Screw Torque: 2±0.5kgf)

S31 Unlock 1 screw to disassemble Docking BD from Main SHD

Disassemble wire from Docking BD





(Screw Torque: 8.5±1.0kgf)

S32 Disassemble Safety mylar from Main SHD



Tear off an adhesive tape from EDP cable on I/F BD

Disconnect EDP cable from I/F BD

Unlock 9 PCBA screws to disassemble I/F BD and SPS BD



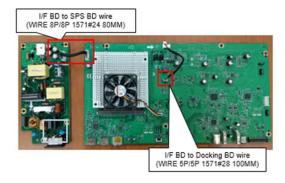
(Screw Torque: 8.5±1kgf)

S34 Disassemble I/F BD and SPS BD from Main SHD



S35 Disconnect I/F BD to Docking BD wire from I/F BD

Disconnect wire from I/F BD and SPS BD



S36 Disconnect Fan Cable from I/F BD



SYNC+Heatsink Module from I/F BD



(Screw Torque: 4.0±0.5 kgf)

Remove electrolyte capacitors (red mark) from printed circuit boards

S38



S38-1 Cut the glue between bulk cap. and PCB with a knife



S38-2 Ensure cutting path within the glue, don't touch bulk cap. or PCB



S38-3 Take out bulk cap. pin solder with soldering iron and absorber



S39-4 Lift the bulk cap. up and away from the PCB



2. Product material information

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

Capacitors / condensers (containing PCB/PCT)	No used
Mercury containing components	No used
Batteries	No used
Printed circuit boards (with a surface greater	Product has printed circuit boards
than 10 square cm)	(with a surface greater than 10 square
	cm)
Component contain toner, ink and liquids	No used
Plastic containing BFR	No used
Component and waste contain asbestos	No used
CRT	No used
Component contain CFC, HCFC, HFC and	No used
HC	
Gas discharge lamps	No used
LCD display > 100 cm2	Product has an LCD greater than 100
	cm2
External electric cable	Product has external cables
Component contain refractory ceramic fibers	No used
Component contain radio-active substances	No used
Electrolyte capacitors (height	Product has electrolyte capacitors
> 25mm, diameter > 25mm)	(height >25mm, diameter > 25mm)

3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:

- Screwdriver
- Scraper Bar
- Penknife
- Soldering iron and absorber